

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary

**RoHS**

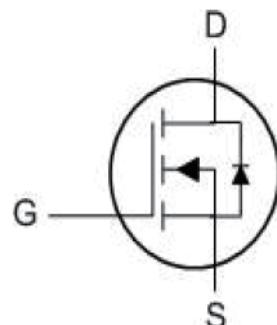
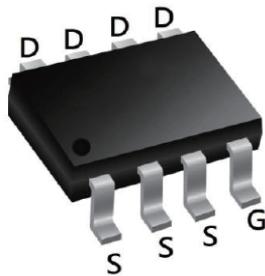
| BVDSS | RDSON | ID  |
|-------|-------|-----|
| 20V   | 8mΩ   | 12A |

### Description

The 2012S is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The 2012S meet the RoHS and Green Product, requirement with full function reliability approved

### SOP8 Pin Configuration



### Absolute Maximum Ratings

| Symbol                               | Parameter   | Rating     | Units |
|--------------------------------------|---|------------|-------|
| V <sub>DS</sub>                      | Drain-Source Voltage                              | 20         | V     |
| V <sub>GS</sub>                      | Gate-Source Voltage                               | ±12        | V     |
| I <sub>D</sub> @T <sub>A</sub> =25°C | Continuous Drain Current, V <sub>GS</sub> @ 4.5V1 | 12         | A     |
| I <sub>D</sub> @T <sub>A</sub> =70°C | Continuous Drain Current, V <sub>GS</sub> @ 4.5V1 | 7          | A     |
| I <sub>DM</sub>                      | Pulsed Drain Current <sup>2</sup>                 | 34         | A     |
| P <sub>D</sub> @T <sub>A</sub> =25°C | Total Power Dissipation <sup>3</sup>              | 3          | W     |
| P <sub>D</sub> @T <sub>A</sub> =70°C | Total Power Dissipation <sup>3</sup>              | 0.86       | W     |
| T <sub>STG</sub>                     | Storage Temperature Range                         | -55 to 150 | °C    |
| T <sub>J</sub>                       | Operating Junction Temperature Range              | -55 to 150 | °C    |

### Thermal Data

| Symbol           | Parameter  | Max. | Unit |
|------------------|--|------|------|
| R <sub>θJA</sub> | Thermal Resistance Junction-ambient <sup>1</sup> | 100  | °C/W |

Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

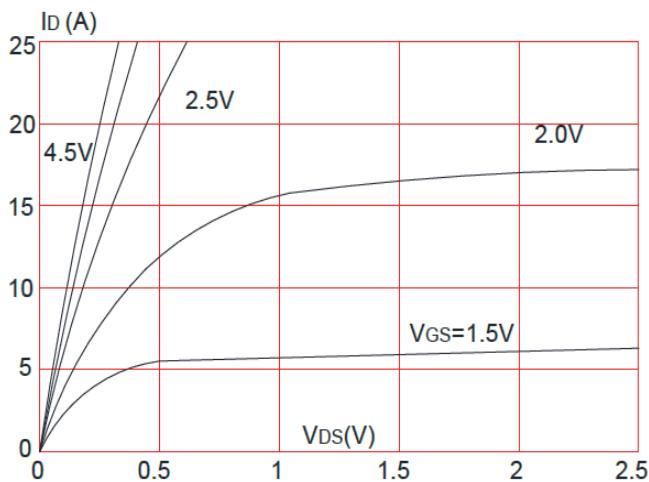
| Symbol  | Parameter  | Test Condition   | Min. | Typ. | Max.      | Units            |
|---|--|--|------|------|-----------|------------------|
| <b>Off Characteristics</b>                                    |  |  |      |      |           |                  |
| $V_{(BR)DSS}$   | Drain-Source Breakdown Voltage                           | $V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$  | 20   | -    | -         | V                |
| $I_{BS}$  | Zero Gate Voltage Drain Current                          | $V_{DS}=20\text{V}$ , $V_{GS}=0\text{V}$ ,   | -    | -    | 1         | $\mu\text{A}$    |
| $I_{GS}$  | Gate to Body Leakage Current                             | $V_{DS}=0\text{V}$ , $V_{GS}=\pm 12\text{V}$   | -    | -    | $\pm 100$ | nA               |
| <b>On Characteristics</b>                                     |  |  |      |      |           |                  |
| $V_{GS(\text{th})}$   | Gate Threshold Voltage                                   | $V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$   | 0.5  | 0.75 | 1.2       | V                |
| $R_{DS(on)}$<br><small>note3</small>                          | Static Drain-Source on-Resistance                        | $V_{GS}=4.5\text{V}$ , $I_D=15\text{A}$  | -    | 8    | 11.2      | $\text{m}\Omega$ |
|   |  | $V_{GS}=2.5\text{V}$ , $I_D=10\text{A}$  | -    | 11.7 | 17.5      |                  |
| <b>Dynamic Characteristics</b>                                |  |  |      |      |           |                  |
| $C_{iss}$   | Input Capacitance  | $V_{DS}=10\text{V}$ , $V_{GS}=0\text{V}$ ,<br>$f=1.0\text{MHz}$                      | -    | 1000 | -         | pF               |
| $C_{oss}$   | Output Capacitance                                       |  | -    | 182  | -         | pF               |
| $C_{rss}$   | Reverse Transfer Capacitance                             |  | -    | 164  | -         | pF               |
| $Q_g$   | Total Gate Charge  | $V_{DS}=10\text{V}$ , $I_D=15\text{A}$ ,<br>$V_{GS}=4.5\text{V}$                     | -    | 15   | -         | nC               |
| $Q_{gs}$  | Gate-Source Charge                                       |  | -    | 2    | -         | nC               |
| $Q_{gd}$  | Gate-Drain("Miller") Charge                              |  | -    | 5.2  | -         | nC               |
| <b>Switching Characteristics</b>                              |  |  |      |      |           |                  |
| $t_{d(on)}$   | Turn-on Delay Time                                       | $V_{DS}=10\text{V}$ , $I_D=15\text{A}$ ,<br>$R_{GEN}=3\Omega$ , $V_{GS}=4.5\text{V}$ | -    | 9    | -         | ns               |
| $t_r$   | Turn-on Rise Time  |  | -    | 25   | -         | ns               |
| $t_{d(off)}$  | Turn-off Delay Time                                      |  | -    | 37   | -         | ns               |
| $t_f$   | Turn-off Fall Time                                       |  | -    | 14   | -         | ns               |
| <b>Drain-Source Diode Characteristics and Maximum Ratings</b> |  |  |      |      |           |                  |
| $I_S$   | Maximum Continuous Drain to Source Diode Forward Current | -  | -    | 40   | -         | A                |
| $I_{SM}$  | Maximum Pulsed Drain to Source Diode Forward Current     | -  | -    | 120  | -         | A                |
| $V_{SD}$  | Drain to Source Diode Forward Voltage                    | $V_{GS}=0\text{V}$ , $I_S=30\text{A}$  | -    | -    | 1.2       | V                |

Notes:

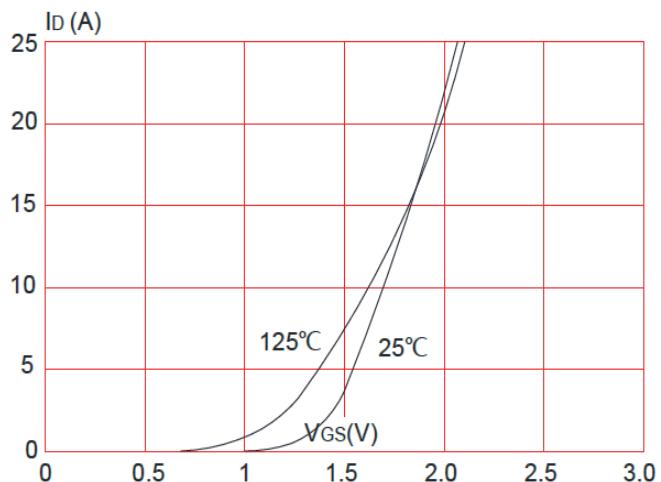
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=10\text{V}$ ,  $V_G=4.5\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_G=25\Omega$ ,  $I_{AS}=9.6\text{A}$
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

### Typical Performance Characteristics

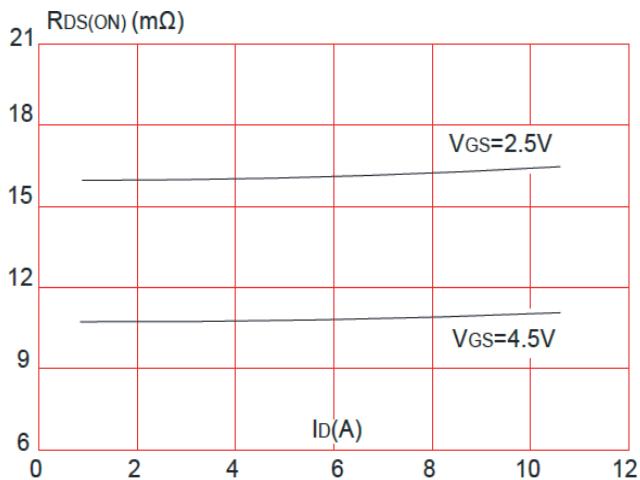
**Figure 1: Output Characteristics**



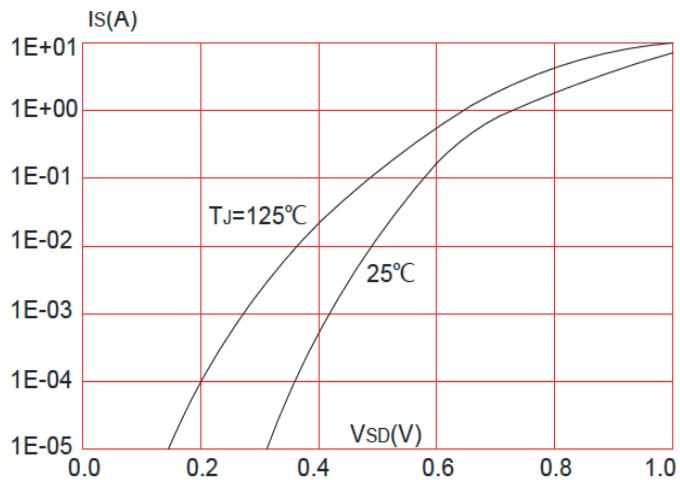
**Figure 2: Typical Transfer Characteristics**



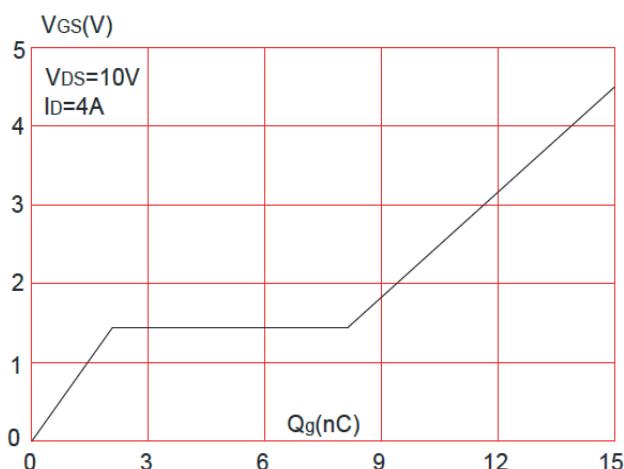
**Figure 3: On-resistance vs. Drain Current**



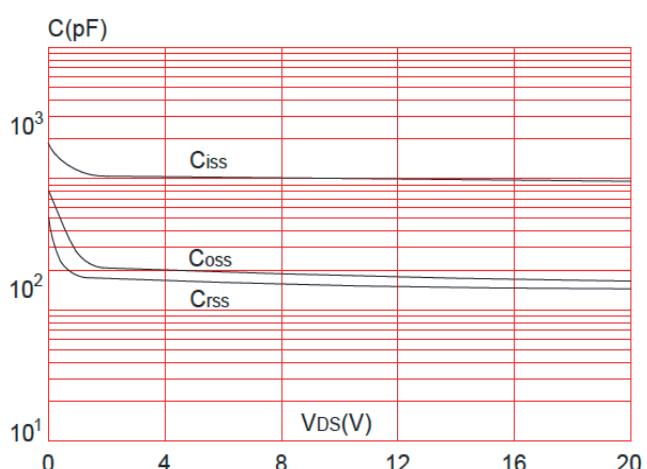
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

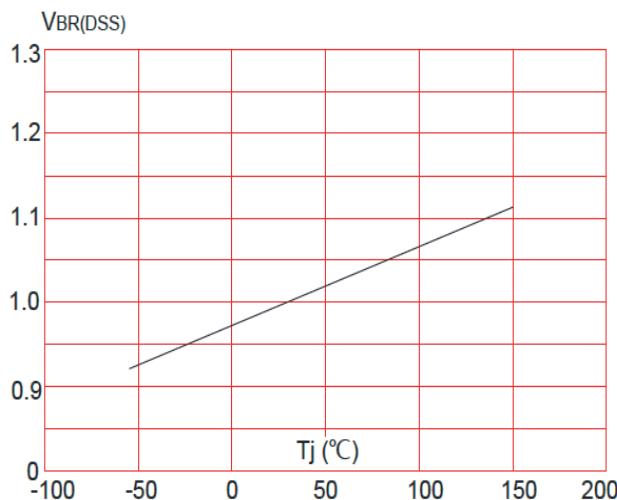


**Figure 6: Capacitance Characteristics**

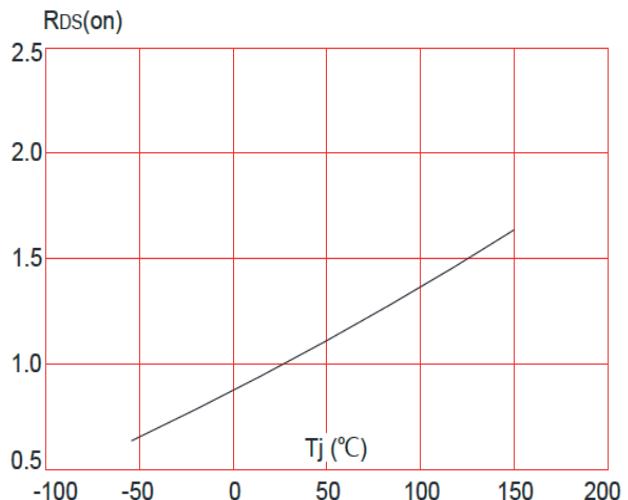


### Typical Performance Characteristics

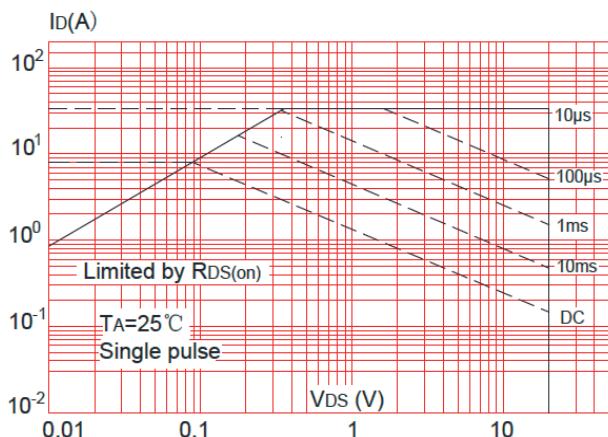
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



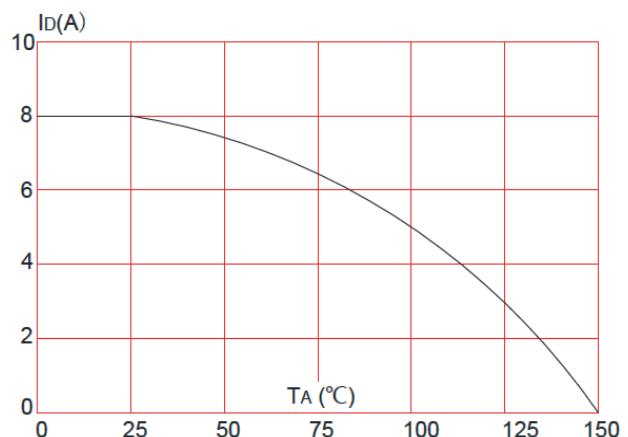
**Figure 8: Normalized on Resistance vs. Junction Temperature**



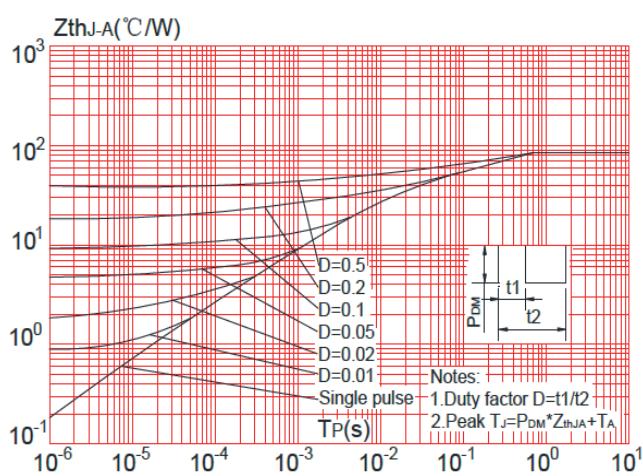
**Figure 8: Maximum Safe Operating Area**



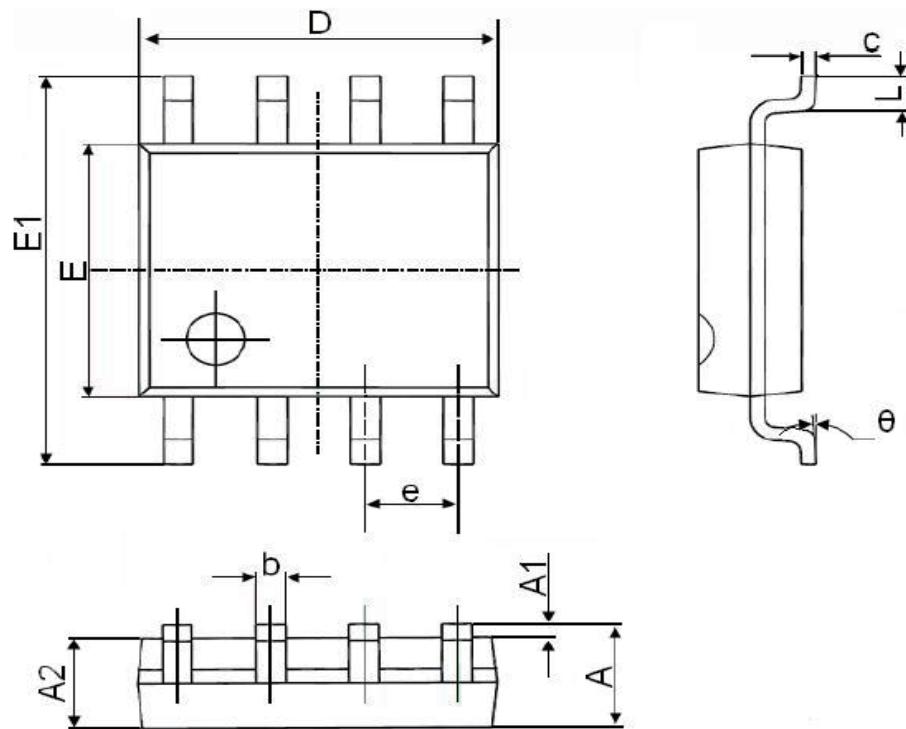
**Figure 9: Maximum Continuous Drain Current vs. Ambient Temperature**



**Figure 10: Maximum Effective Transient Thermal Impedance, Junction to Ambient**



## SOP-8 Package Information



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min.                      | Max.  | Min.                 | Max.  |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.013                | 0.020 |
| c      | 0.170                     | 0.250 | 0.006                | 0.010 |
| D      | 4.700                     | 5.100 | 0.185                | 0.200 |
| E      | 3.800                     | 4.000 | 0.150                | 0.157 |
| E1     | 5.800                     | 6.200 | 0.228                | 0.244 |
| e      | 1.270(BSC)                |       | 0.050(BSC)           |       |
| L      | 0.400                     | 1.270 | 0.016                | 0.050 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |